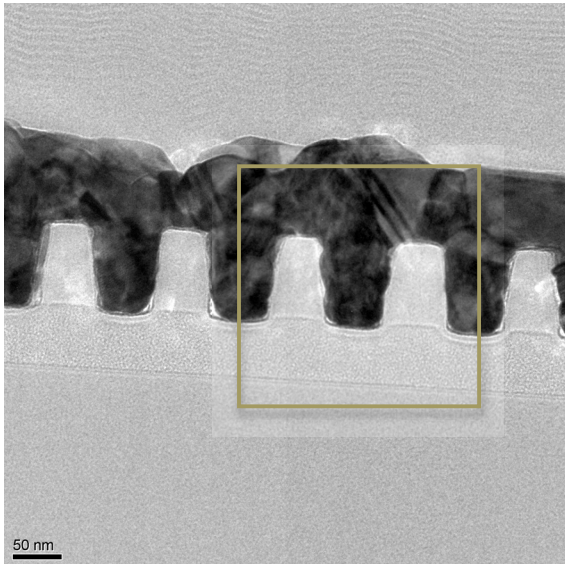


Process results examples: MOCVD Cu

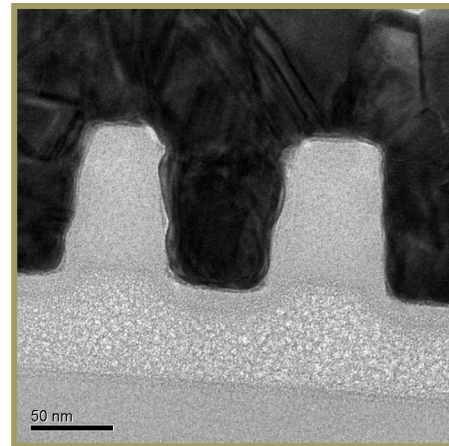
- For TSV applications

First integration results



*TiN/Cu CVD in vias
60nm width - 100nm deep*

(Photos: courtesy of TU Chemnitz)



Cu CVD from CupraSelect with 5nm TiN